



THE DATASHEET OF MPC565MZP56



Product Brief

MPC565PB/D
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MPC565/MPC566
Product Brief


This document provides an overview of the MPC565/MPC566 microcontrollers, including a block diagram showing the major modular components, sections that list the major features, and differences between the MPC565/MPC566 and the MPC555. The MPC565 and MPC566 devices are members of the Motorola MPC500 RISC Microcontroller family. The parts herein will be referred to only as MPC565 unless specific parts need to be referenced.

Table 1. MPC565/MPC566 Features

Device	Flash	Code Compression
MPC565	1 Mbyte	Code compression not supported
MPC566	1 Mbyte	Code compression supported

1 Introduction

The MPC565 device offers the following features:

- PowerPC™ core with a floating point unit (FPU) and a burst buffer controller (BBC)
- Unified system integration unit (USIU), a flexible memory controller, and improved interrupt controller
- 1 Mbyte of Flash memory (UC3F)
 - Typical endurance of 100,000 write/erase cycles @ 25°C
 - Typical data retention of 100 years @ 25°C
- 36 Kbytes of static RAM (two CALRAM modules)
 - 8 Kbytes of normal access or overlay access (sixteen 512-byte regions)
 - 4 Kbytes in CALRAM A, 4 Kbytes in CALRAM B
- Three time processor units (TPU3)
 - TPU3 A and TPU3 B are connected to DPTRAM AB (6 Kbytes)
 - TPU3 C is connected to DPTRAM C (4 Kbytes)
- A 22-timer channel modular I/O system (MIOS14)
 - Same as MIOS1 plus a real-time clock sub-module (MRTCSM), 4 counter sub-modules (MCSM), and 4 PWM sub-modules (MPWMSM)
- Three TouCAN modules (TouCAN_A, TouCAN_B, and TouCAN_C)
- Two enhanced queued analog to digital converters (QADC64E A, QADC64E B) with analog multiplexers (AMUX) for 40 total analog channels. These modules are configured so each module can access all 40 of the analog inputs to the part.

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Block Diagram

- Two queued serial multi-channel modules (QSMCM A, QSMCM B), each of which contains a queued serial peripheral interface (QSPI) and two serial controller interfaces (SCI/UART)
- -40°C – 125°C ambient temperature, -40°C – 85°C for suffix C devices, -55°C– 125°C for suffix A devices
- Debug features:
 - A J1850 (DLCMD2) communications module
 - A Nexus debug port (class 3) – IEEE-ISTO 5001-1999
 - JTAG and background debug mode (BDM)
- Packaging and Electrical

1.1 Block Diagram

Figure 1 is a block diagram of the MPC565.

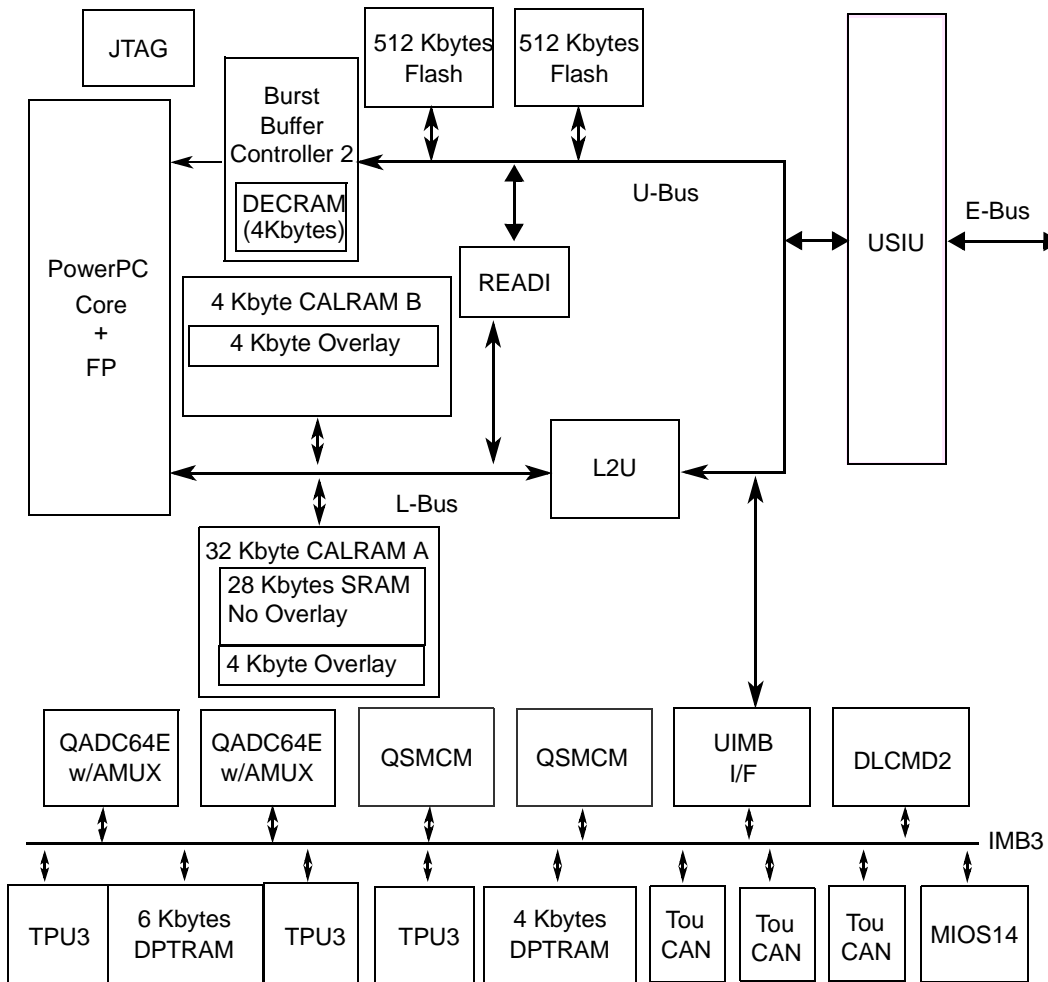


Figure 1. MPC565 Block Diagram

1.2 Detailed Feature List

The MPC565 key features are explained in the following sections.

1.2.1 High Performance CPU System

- Fully static design
- Four major power saving modes
 - On, doze, sleep, deep-sleep and power-down

1.2.2 RISC MCU Central Processing Unit (RCPU)

- High-performance core
 - PowerPC single issue integer core
 - Precise exception model
 - Floating point
 - Code compression (MPC566 only)
 - Compression reduces usage of internal or external Flash memory
 - Compression optimized for automotive (non-cached) applications
 - New compression scheme decreases code size to 40% –50% of source

1.2.3 MPC500 System Interface (USIU)

- MPC500 system interface (USIU, BBC, L2U)
- Periodic interrupt timer, bus monitor, clocks, decremter and time base
- Clock synthesizer, power management, reset controller
- External bus tolerates 5-V inputs, provides 2.6-V outputs
- Enhanced interrupt controller supports a separate interrupt vector for up to eight external and 40 internal interrupts
- IEEE 1149.1 JTAG test access port
- Bus supports multiple master designs
- USIU supports dual-mapping of Flash to move part of internal Flash memory to external bus for development
- External bus, supporting non-wraparound burst for instruction fetches, with up to 8 instructions per memory cycle

1.2.4 Burst Buffer Controller (BBC) Module

- Exception vector table relocation features allow exception table to be relocated to following locations:
 - 0x0000 0000 - 0x0000 1FFF (normal MPC500 exception table location)
 - 0x0001 0000 - 0x0001 1FFF (0 + 64 Kbytes; second page of internal Flash)
 - Second internal Flash module
 - Internal SRAM
 - 0x0FFF_0100 (external memory space; normal MPC500 exception table location)

1.2.5 Flexible Memory Protection Unit

- Flexible memory protection units in BBC (IMPU) and L2U (DMPU)
- Default attributes available in one global entry
- Attribute support for speculative accesses

1.2.6 Memory Controller

- Flexible chip selects via memory controller
- 24-bit address and 32-bit data buses
- 4- to 16-Mbyte (data) or 4-Gbyte (instruction) region size support
- Four-beat transfer bursts, two-clock minimum bus transactions
- Use with SRAM, EPROM, Flash and other peripherals
- Byte selects or write enables
- 32-bit address decodes with bit masks
- Four instruction regions
- Four data regions

1.2.7 1 Mbyte of CDR3 Flash EEPROM Memory (UC3F)

- 1 Mbyte Flash
 - Two UC3F modules, 512 Kbytes each
- Page mode read
- Block (64-Kbyte) erasable
- External 4.75- to 5.25-V VPP program and erase power supply
- Typical endurance of 100,000 write/erase cycles @ 25°C
- Typical data retention of 100 years @ 25°C

1.2.8 36-Kbyte Static RAM (CALRAM)

- 36-Kbyte static calibration RAM
 - Composed of 4-Kbyte and 32-Kbyte CALRAM modules
- Fast access: one clock
- Keep-alive power
- Soft defect detection (SDD)
- 4 Kbyte calibration (overlay) RAM per module (8 Kbytes total)
- Eight 512-byte overlay regions per module (16 regions total)

1.2.9 General Purpose I/O Support (GPIO)

- General-purpose I/O support
- Address (24) and data (32) pins can be used as GPIO in single-chip mode
- 16 GPIO in MIOS14
- Many peripheral pins can be used as GPIO when not used as primary functions
- 5-V outputs with slew rate control

1.2.10 Debug Features

- Extensive system debug support
- On-chip watchpoints and breakpoints
- Program flow tracking
- Background debug mode (BDM)

1.2.10.1 Nexus Debug Port (Class 3)

- Nexus/IEEE – ISTO 5001-1999 debug port (Class 3)
- Nine- or 16-pin interface

1.2.10.2 Message Data Link Controller (DLCMD2) Module

- Two pins muxed with QSMCMB pins. Muxing controlled by QSMCMB PCS3 pin assignment register
- SAE J1850 Class B data communications network interface compatible and ISO compatible for low-speed (<125 Kbps) serial data communications in automotive applications
- 10.4 Kbps variable pulse width (VPW) bit format
- Digital noise filter, collision detection
- Hardware cyclical redundancy check (CRC) generation and checking
- Block mode receive and transmit supported
- 4x receive mode supported (41.6 Kbps)
- Digital loopback mode
- In-frame response (IFR) types 0, 1, 2, and 3 supported
- Dedicated register for symbol timing adjustments
- Inter-module bus 3 (IMB3) slave interface
- Power-saving IMB3 stop mode with automatic wakeup on network activity
- Power-saving IMB3 CLOCKDIS mode
- Debug mode available through IMB3 FREEZE signal or user controllable SOFT_FRZ bit
- Polling and IMB3 interrupt generation with vector lookup available

1.2.11 Integrated I/O System

- True 5-V I/O

1.2.11.1 Time Processor Units (TPU3)

- Three time processing units (TPU3)
 - 16 channels each
- Each TPU3 is a microcoded timer subsystem
- One 6-Kbyte and one 4-Kbyte dual-port TPU RAM (DPTRAM), one (6-Kbyte) shared by two TPU3 modules for TPU microcode and the 4-Kbyte dedicated to the third TPU3 for microcode.

1.2.11.2 22-Channel Modular I/O System (MIOS14)

- 22-channel MIOS timer (MIOS14)
- Six modulus counter submodules (MCSM)
 - Four additional MCSM submodules compared to MIOS1
- 10 double action submodules (DASM).
- 12 dedicated PWM submodules (PWMSM)
 - Four additional PWM submodules compared to MIOS1 (shared with MIOS GPIO pins)
- MIOS real-time clock submodule (MRTCSM) provides low power clock/counter
 - Requires external 32-KHz crystal
 - Uses four pins: two for 32-KHz crystal, two for power/ground.

1.2.12 Two Enhanced Queued Analog-to-Digital Converter Modules (QADC64E)

- Two enhanced queued analog to digital converters (QADC64E A, QADC64E B) with AMUXes for 40 total analog channels.
- 10 bit A/D converter with internal sample/hold
 - Typical conversion time is 4 μ s (250-Kbyte samples/sec)
 - Two conversion command queues of variable length
- Automated queue modes initiated by:
 - External edge trigger/level gate
 - Software command
 - Periodic/interval timer, assignable to both queue 1 and 2
- 64 result registers in each QADC64E module
 - Output data is right or left justified, signed or unsigned
- Synchronized clock mode allows both QADC64Es to see the same conversion clock. This allows the two modules to look like one large QADC with four queues.
- Conversions alternate reference (ALTREF) pin. This pin can be connected to a different reference voltage

1.2.13 Three CAN 2.0B Controller (TouCAN) Modules

- Three TouCAN modules (TouCAN_A, TouCAN_B, and TouCAN_C)
- 16 message buffers each, programmable I/O modes
- Maskable interrupts
- Programmable loopback for self-test operation
- Independent of the transmission medium (external transceiver is assumed)
- Open network architecture, multimaster concept
- High immunity to EMI
- Short latency time for high-priority messages
- Low power sleep mode, with programmable wake up on bus activity
- TouCAN_C pins shared with MIOS14 GPIO pins

1.2.14 Queued Serial Multi-Channel Modules (QSMCM)

- Two queued serial modules with one queued-SPI and two SCI each (QSMCM_A, QSMCM_B)
 - QSMCM_A matches full MPC555 QSMCM functionality
 - QSMCM_B has pins muxed with DLCMD2 module
 - Two pins are muxed with DLCMD2 (J1850) transmit and receive pins (B_PCS3_J1850_TX and B_RXD2_J1850_RX)
 - QSMCM B vs J1850 mux control provided by QPAPCS3 bit in QSMCM pin assignment register (PQSPAR)
- Queued-SPI
 - Provides full-duplex communication port for peripheral expansion or interprocessor communication
 - Up to 32 preprogrammed transfers, reducing overhead
 - Synchronous serial interface with baud rate of up to system clock / 4
 - Four programmable peripheral-select pins support up to 16 devices
 - Special wrap-around mode allows continuous sampling of a serial peripheral for efficient interfacing to serial analog-to-digital (A/D) converters
- SCI
 - UART mode provides NRZ format and half- or full-duplex interface
 - 16 register receive buffer and 16 register transmit buffer on one SCI
 - Advanced error detection, and optional parity generation and detection
 - Word length programmable as 8 or 9 bits
 - Separate transmitter and receiver enable bits, and double buffering of data
 - Wake-up functions allow the CPU to run uninterrupted until either a true idle line is detected, or a new address byte is received

1.2.15 Electrical Specifications and Packaging

- 40 MHz operation (56 MHz operation is optional for the MPC566)
- -40°C – 125°C ambient temperature, -40°C – 85°C for suffix C device, -55°C– 125°C for suffix A devices
- 2.6 V \pm 0.1 V external bus
 - External bus is compatible with external memory devices operating from 2.5 V to 3.4 V.
 - Extended voltage range (2.7 – 3.4 V) degrades data drive timing by 1.1 ns on data writes.
- 2.6 \pm 0.1 V internal logic
- 5-V I/O (5.0 \pm 0.25 V)
- Available in package or bumped die
- Plastic ball grid array (PBGA) packaging
 - 388 ball PBGA
 - 27 mm x 27 mm body size
- 1.0 mm ball pitch

1.3 MPC565 Optional Features

The following features of the MPC565 are optional features and may not appear in certain configurations:

- 56-MHz operation (40-MHz is default)
- MPC566 supports code compression

2 Differences between the MPC565 and the MPC555

The MPC565 is an enhanced version of the MPC555. Most functional features of the MPC555 are unchanged on the MPC565. Table 2 shows the high level differences.

Table 2. Differences Between Modules of the MPC555 and the MPC565

Module	MPC555	MPC565
CPU Core	No Change	
BBC	BBC	BBC with improved code compression ¹
L2U	No Change	
SRAM	26-Kbytes	36-Kbyte CALRAM with overlay features
Flash	448-Kbyte CMF	1-Mbyte UC3F (new programming, etc.)
USIU	USIU	USIU with enhanced interrupt controller
JTAG	No Change	
READI	None	New Module
UIMB	No Change	
QADC64	2 QADC64 (16 channels on each QADC for 32 total channels)	2 QADC64E w/AMUXes (40 channels accessible from either QADC64E)
QSMCM	(1) No Change (2)	
DLCMD2 (J1850)	None	1
MIOS	MIOS1	MIOS14: MIOS1 with real-time clock (MRTCSM), 4 more PWMSMs and 4 more MCSMs
TouCAN	(2) No Change (3)	
TPU3	(2) No Change (3)	
DPTRAM	(6-Kbytes) No Change (6-Kbytes, 4-Kbytes)	
Power Supplies		
—	40 MHz with two power supplies: nominal 3.3-V to 5.0-V power supplies	56 MHz with two power supplies: 5.0-V I/O, 2.6-V internal logic

¹ Available on some options.

2.1 Additional MPC565 Differences

The following are additional differences between the MPC555 and the MPC565.

- SPI (MISO, MOSI, and SCK) pin drive.
 - MPC565 provides 21-ns rise/fall with 200-pf load using CMOS (20%/70%) levels
- GPIO on MODCK1 pin outputs only 2.6 V
 - MODCK1 pin is in keep-alive power section with no 5-V rail available
 - 5.0-V compatibility modes
 - Input is 5-V friendly
 - 2.6-V output has less slew rate control
 - 2.6-V: $V_{OH} = 2.3\text{ V}$
- Power supplies for external bus pins
 - QVDDL is quiet supply to hold non-switching outputs quiet even when noisy supply (NVDDL) sags
 - QVDDL supplies pre-drive and other pad logic
 - NVDDL only supplies final PMOS driver stage
 - QVDDL and NVDDL shorted on customer board after filtering
- Pull-up and pull-down changes during PORESET and HRESET
 - All 2.6-V/5-V pads (external bus: address/data/control) pull down at reset
 - All 5-V pads pull up at reset
 - Additional control granularity in the PDMCR register
- No pull-ups on QSMCM SCI receive pads
- A_RXD1_QGPI1, A_RXD2_QGPI2, B_RXD1_QGPI1 pins do not have weak pull-up during reset or any other time
- CLKOUT has 3 drive strength options
 - Better matches drive to requirements to reduce EMI
 - 25, 50, 100 pf instead of 45 and 90 pf
- Change reset value of ENGCLK to maximum divide (crystal/128)
 - For a 4-MHz crystal, this is 31.25 KHz
 - ENGCLK is selectable between 2.6 V and 5 V
- A daisy chain between UC3F modules allows either module to provide the reset configuration word (RCW)
- Censorship operation
 - A RCW bit controls whether or not the entire UC3F can be erased while censorship is violated
- BBC SPRs (PPC regs) access in two clocks instead of one clock
- CALRAM internal protection block size is 8 Kbytes
 - Instead of 4 Kbytes on MPC555 LRAM
- CALRAM causes machine check exception instead of data storage interrupt (DSI) exception in certain cases
 - For non-overlay CPU core accesses, a DSI exception is taken
 - For overlay accesses and any non-core access (slave mode), a machine check exception is taken

- CALRAM causes DSI exception only if the data relocation (DR) bit in the core machine state register, MSR[DR], is set.
 - L2U on MPC555 already followed this protocol, but the LRAM did not. Now all L-bus peripherals follow this protocol.
 - The MSR[DR] bit is described in the reference manual for more information.
- Four additional PRDS control bits were added to the USIU to allow more granularity of PRDS control on a part
- BBC includes a 4-Kbyte DECRAM that can be used if compression is not used or is not available.

3 SRAM Keep-Alive Power Behavior

The SRAM has three keep-alive power pins (VDDSRAM1, VDDSRAM2, and VDDSRAM3). These pins provide keep-alive power to the SRAM arrays in the CALRAM modules and the DPTRAM modules.

The VDDSRAM1 pin powers the 32-Kbyte CALRAM A during keep-alive while power is off to the MPC565 (except for the keep-alive power supplies). CALRAM A keeps all of its 32 Kbytes powered during power down.

The VDDSRAM2 pin powers the 4-Kbyte CALRAM B module. The VDDSRAM3 pin powers the DPTRAM modules during keep-alive as well as during normal operation. The CALRAM modules only power their arrays from the VDDSRAM pins during keep-alive. During normal operation, they are powered by the normal internal VDD of the part.

The DPTRAM modules (6 Kbytes and 4 Kbytes) and the 4-Kbyte DECRAM in the BBC module power their arrays via the VDDSRAM3 pin during keep-alive and are supplied by VDD during normal operation.

4 MPC565 Memory Map

The internal memory map is organized as a single 4-Mbyte block. This is shown in Figure 3. This block can be moved to one of eight different locations. The internal memory space is divided into the following sections:

- Flash memory (1 Mbyte) — U-bus memory
- Static RAM memory (36 Kbytes CALRAM) — L-bus memory
- Control registers and IMB3 modules (64 Kbytes), partitioned as
 - USIU and flash control registers
 - UIMB interface and IMB3 modules
 - CALRAM and READI control registers (L-bus control register space)

The internal memory block can reside in one of eight possible 4-Mbyte memory spaces. These eight locations are the first eight 4-Mbyte memory blocks starting with address 0x0000 0000, as shown in Figure 2. There is a user programmable register in the USIU to configure the internal memory map to one of the eight possible locations. Programmability of internal memory map location allows multiple chip system.

The IMB3 address space block in Figure 3 shows memory allocation for IMB3 modules. It does not show the actual memory space required for individual modules. All modules are mapped to the low address, numerically, of the memory allocated for that module in the IMB3 address space.

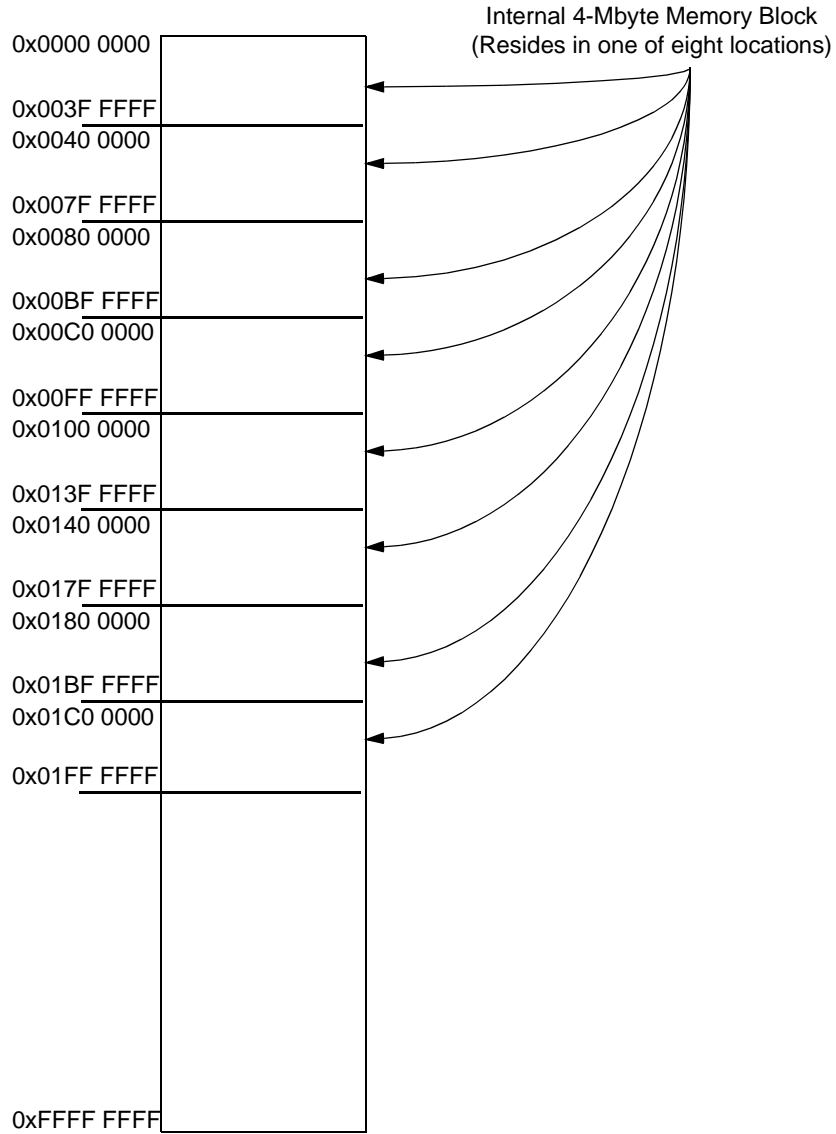


Figure 2. Memory Map

0x00 0000	UC3F_A Flash 512 Kbytes	USIU Control Registers	0x2F C000
0x07 FFFF		UC3F_A Control (64 bytes)	0x2F C800
0x08 0000	UC3F_B Flash 512 Kbytes	UC3F_B Control (64 bytes)	0x2F C840
0x0F FFFF			0x2F C87F
0x10 0000	Reserved for Flash (2,016 Kbytes)		
0x2F 7FFF		DPTRAM_AB Registers (64 bytes)	0x30 0000
0x2F 8000	DECRAM 4 Kbytes	DPTRAM_C Registers (64 bytes)	0x30 0040
0x2F 8FFF		DLCMD2 (16 bytes)	0x30 0080
0x2F 9000	Reserved	Reserved (3952 bytes)	0x30 0090
0x2F 9FFF			
0x2F A000	BBC Control Registers 8 Kbytes	DPTRAM_C (4 Kbytes)	0x30 1000
0x2F BFFF		DPTRAM_AB (6 Kbytes)	0x30 2000
0x2F C000	USIU & Flash Control 16 Kbytes	Reserved (2 Kbytes)	0x30 3800
0x2F FFFF		TPU3_A (1 Kbytes)	0x30 4000
0x30 0000	UIMB I/F & IMB Modules 32 Kbytes	TPU3_B (1 Kbytes)	0x30 4400
0x30 7FFF		QADC64_A (1 Kbytes)	0x30 4800
0x30 8000	Reserved for IMB 480 Kbytes	QADC64_B (1 Kbytes)	0x30 4C00
0x37 FFFF		QSMCM_A (1 Kbytes)	0x30 5000
0x38 0000	CALRAM/ Readi Control 256 bytes	QSMCM_B (1 Kbytes)	0x30 5400
0x38 00FF		Reserved (1 Kbytes)	0x30 5800
0x38 0100	Reserved (L-bus Control) ~32 Kbytes	TPU3_C (1 Kbytes)	0x30 5C00
0x38 3FFF		MIOS14 (4 Kbytes)	0x30 6000
0x38 4000	Reserved (L-bus Mem) 444 Kbytes	TOUCAN_A (1 Kbytes)	0x30 7000
0x3F 6FFF		TOUCAN_B (1 Kbytes)	0x30 7400
0x3F 7000	All 4-Kbytes can be Overlay Section	TOUCAN_C (1 Kbytes)	0x30 7800
0x3F 7FFF	CALRAM_B (4 Kbyte)	Reserved (896 bytes)	0x30 7900
0x3F 8000		UIMB Control Registers (128 bytes)	0x30 7F80
	CALRAM_A (32 Kbyte)		0x30 7FFF
0x3F FFFF	4-Kbyte Overlay Section		

Figure 3. Internal Memory Block

5 MPC565 Pinout Diagram

Figure 4 shows the pinout for the MPC565.

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	
A	VDD ANV_B_PCB0	VBI ANV_A_PCB0	VBI ALTRF	VBI ANV_A_PCB1	AMB ANV_A_PCB2	AMB ANV_A_PCB3	AMB ANV_A_PCB4	AMB ANV_A_PCB5	AMB ANV_A_PCB6	AMB ANV_A_PCB7	AMB ANV_A_PCB8	AMB ANV_A_PCB9	AMB ANV_A_PCB10	AMB ANV_A_PCB11	AMB ANV_A_PCB12	AMB ANV_A_PCB13	AMB ANV_A_PCB14	AMB ANV_A_PCB15	AMB ANV_A_PCB16	AMB ANV_A_PCB17	AMB ANV_A_PCB18	AMB ANV_A_PCB19	AMB ANV_A_PCB20	AMB ANV_A_PCB21	AMB ANV_A_PCB22	
B	VSS	VDD ANV_B_PCB0	VDD ANV_B_PCB1	VDD ANV_B_PCB2	VDD ANV_B_PCB3	VDD ANV_B_PCB4	VDD ANV_B_PCB5	VDD ANV_B_PCB6	VDD ANV_B_PCB7	VDD ANV_B_PCB8	VDD ANV_B_PCB9	VDD ANV_B_PCB10	VDD ANV_B_PCB11	VDD ANV_B_PCB12	VDD ANV_B_PCB13	VDD ANV_B_PCB14	VDD ANV_B_PCB15	VDD ANV_B_PCB16	VDD ANV_B_PCB17	VDD ANV_B_PCB18	VDD ANV_B_PCB19	VDD ANV_B_PCB20	VDD ANV_B_PCB21	VDD ANV_B_PCB22		
C	VDDRTC	VSS	VDD ANV_A_PCB1	VDD ANV_B_PCB1	VDD ANV_A_PCB2	VDD ANV_B_PCB2	VDD ANV_A_PCB3	VDD ANV_B_PCB3	VDD ANV_A_PCB4	VDD ANV_B_PCB4	VDD ANV_A_PCB5	VDD ANV_B_PCB5	VDD ANV_A_PCB6	VDD ANV_B_PCB6	VDD ANV_A_PCB7	VDD ANV_B_PCB7	VDD ANV_A_PCB8	VDD ANV_B_PCB8	VDD ANV_A_PCB9	VDD ANV_B_PCB9	VDD ANV_A_PCB10	VDD ANV_B_PCB10	VDD ANV_A_PCB11	VDD ANV_B_PCB11	VDD ANV_A_PCB12	VDD ANV_B_PCB12
D	EXTAL32	VDD32K	VSS	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	
E	XITAL32	B_CMTX6	VDD32K	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	
F	VSSRTC	C_TRU008	C_TRU009	MD01	MD02	MD03	MD04	MD05	MD06	MD07	MD08	MD09	MD10	MD11	MD12	MD13	MD14	MD15	MD16	MD17	MD18	MD19	MD20	MD21	MD22	
G	C_TRU010	C_TRU011	C_TRU012	VDD32K	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	
H	C_TRU013	C_TRU014	C_TRU015	C_TRU016	C_TRU017	C_TRU018	C_TRU019	C_TRU020	C_TRU021	C_TRU022	C_TRU023	C_TRU024	C_TRU025	C_TRU026	C_TRU027	C_TRU028	C_TRU029	C_TRU030	C_TRU031	C_TRU032	C_TRU033	C_TRU034	C_TRU035	C_TRU036	C_TRU037	
J	C_TRU038	C_TRU039	C_TRU040	C_TRU041	C_TRU042	C_TRU043	C_TRU044	C_TRU045	C_TRU046	C_TRU047	C_TRU048	C_TRU049	C_TRU050	C_TRU051	C_TRU052	C_TRU053	C_TRU054	C_TRU055	C_TRU056	C_TRU057	C_TRU058	C_TRU059	C_TRU060	C_TRU061	C_TRU062	
K	C_TRU063	C_TRU064	C_TRU065	C_TRU066	C_TRU067	C_TRU068	C_TRU069	C_TRU070	C_TRU071	C_TRU072	C_TRU073	C_TRU074	C_TRU075	C_TRU076	C_TRU077	C_TRU078	C_TRU079	C_TRU080	C_TRU081	C_TRU082	C_TRU083	C_TRU084	C_TRU085	C_TRU086	C_TRU087	
L	MDL0	TDC_DSEK	MDL1	MCKI	MDL2	MDL3	MDL4	MDL5	MDL6	MDL7	MDL8	MDL9	MDL10	MDL11	MDL12	MDL13	MDL14	MDL15	MDL16	MDL17	MDL18	MDL19	MDL20	MDL21	MDL22	
M	MDL23	MDL24	MDL25	MDL26	MDL27	MDL28	MDL29	MDL30	MDL31	MDL32	MDL33	MDL34	MDL35	MDL36	MDL37	MDL38	MDL39	MDL40	MDL41	MDL42	MDL43	MDL44	MDL45	MDL46	MDL47	
N	MDL48	MDL49	MDL50	MDL51	MDL52	MDL53	MDL54	MDL55	MDL56	MDL57	MDL58	MDL59	MDL60	MDL61	MDL62	MDL63	MDL64	MDL65	MDL66	MDL67	MDL68	MDL69	MDL70	MDL71	MDL72	
P	MDL73	MDL74	MDL75	MDL76	MDL77	MDL78	MDL79	MDL80	MDL81	MDL82	MDL83	MDL84	MDL85	MDL86	MDL87	MDL88	MDL89	MDL90	MDL91	MDL92	MDL93	MDL94	MDL95	MDL96	MDL97	
R	MDL98	MDL99	MDL100	MDL101	MDL102	MDL103	MDL104	MDL105	MDL106	MDL107	MDL108	MDL109	MDL110	MDL111	MDL112	MDL113	MDL114	MDL115	MDL116	MDL117	MDL118	MDL119	MDL120	MDL121	MDL122	
T	MDL123	MDL124	MDL125	MDL126	MDL127	MDL128	MDL129	MDL130	MDL131	MDL132	MDL133	MDL134	MDL135	MDL136	MDL137	MDL138	MDL139	MDL140	MDL141	MDL142	MDL143	MDL144	MDL145	MDL146	MDL147	
U	MDL148	MDL149	MDL150	MDL151	MDL152	MDL153	MDL154	MDL155	MDL156	MDL157	MDL158	MDL159	MDL160	MDL161	MDL162	MDL163	MDL164	MDL165	MDL166	MDL167	MDL168	MDL169	MDL170	MDL171	MDL172	
V	MDL173	MDL174	MDL175	MDL176	MDL177	MDL178	MDL179	MDL180	MDL181	MDL182	MDL183	MDL184	MDL185	MDL186	MDL187	MDL188	MDL189	MDL190	MDL191	MDL192	MDL193	MDL194	MDL195	MDL196	MDL197	
W	MDL198	MDL199	MDL200	MDL201	MDL202	MDL203	MDL204	MDL205	MDL206	MDL207	MDL208	MDL209	MDL210	MDL211	MDL212	MDL213	MDL214	MDL215	MDL216	MDL217	MDL218	MDL219	MDL220	MDL221	MDL222	
Y	MDL223	MDL224	MDL225	MDL226	MDL227	MDL228	MDL229	MDL230	MDL231	MDL232	MDL233	MDL234	MDL235	MDL236	MDL237	MDL238	MDL239	MDL240	MDL241	MDL242	MDL243	MDL244	MDL245	MDL246	MDL247	
AA	MDL248	MDL249	MDL250	MDL251	MDL252	MDL253	MDL254	MDL255	MDL256	MDL257	MDL258	MDL259	MDL260	MDL261	MDL262	MDL263	MDL264	MDL265	MDL266	MDL267	MDL268	MDL269	MDL270	MDL271	MDL272	
AB	MDL273	MDL274	MDL275	MDL276	MDL277	MDL278	MDL279	MDL280	MDL281	MDL282	MDL283	MDL284	MDL285	MDL286	MDL287	MDL288	MDL289	MDL290	MDL291	MDL292	MDL293	MDL294	MDL295	MDL296	MDL297	
AC	MDL298	MDL299	MDL300	MDL301	MDL302	MDL303	MDL304	MDL305	MDL306	MDL307	MDL308	MDL309	MDL310	MDL311	MDL312	MDL313	MDL314	MDL315	MDL316	MDL317	MDL318	MDL319	MDL320	MDL321	MDL322	
AD	MDL323	MDL324	MDL325	MDL326	MDL327	MDL328	MDL329	MDL330	MDL331	MDL332	MDL333	MDL334	MDL335	MDL336	MDL337	MDL338	MDL339	MDL340	MDL341	MDL342	MDL343	MDL344	MDL345	MDL346	MDL347	
AE	MDL348	MDL349	MDL350	MDL351	MDL352	MDL353	MDL354	MDL355	MDL356	MDL357	MDL358	MDL359	MDL360	MDL361	MDL362	MDL363	MDL364	MDL365	MDL366	MDL367	MDL368	MDL369	MDL370	MDL371	MDL372	
AF	MDL373	MDL374	MDL375	MDL376	MDL377	MDL378	MDL379	MDL380	MDL381	MDL382	MDL383	MDL384	MDL385	MDL386	MDL387	MDL388	MDL389	MDL390	MDL391	MDL392	MDL393	MDL394	MDL395	MDL396	MDL397	

NOTE: This is a top down view of the balls.

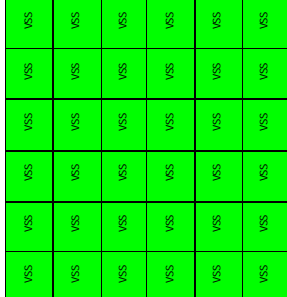


Figure 4. MPC565 Pinout Diagram



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